Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-01-28
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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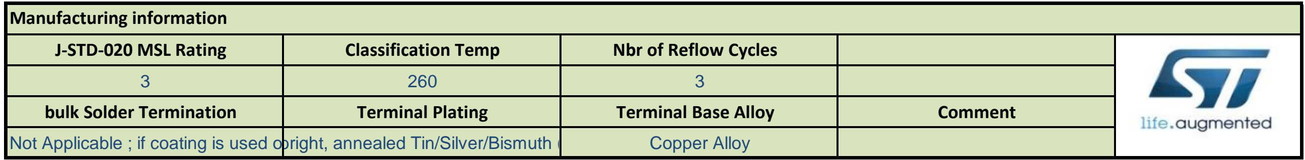
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
VN5025AJTR-E	AR0T*VNJ6AFC	A	BO2A	2013-01-28
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	1115.00	mg	Each	ECOPACK® 1



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used o	bright, annealed Tin/Silver/Bismuth (	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
CHP	4.9x3.9x1.55	12	flat	
Comment				

Material Composition Declaration						Mfr Item Name	AR0T*VNJ6AFC					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	3.575	mg	supplier	die	Silicon (Si)	7440-21-3		3.451	mg	965315	3095
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.031	mg	8671	28
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.028	mg	7832	25
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.029	mg	8112	26
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	559	2
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1678	5
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.026	mg	7273	23
die (s)				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	559	2
Leadframe	Copper & its alloys	67.153	mg	supplier	alloy	Copper (Cu)	7440-50-8		66.333	mg	987789	59491
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.031	mg	462	28
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.056	mg	834	50
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.733	mg	10915	657
Die attach		3.169	mg	JIG R	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high me	3.027	mg	955191	2715
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.079	mg	24929	71
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.063	mg	19880	57
Bonding wire		0.313		supplier	wire	Gold (Au)	7440-57-5		0.062	mg	198083	56
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.251	mg	801917	225
encapsulation		1040.015	mg	supplier	mold compound	Silica, vitreous	60676-86-0		832.012	mg	800000	746199
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		72.801	mg	70000	65292
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		41.6	mg	39999	37309
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		62.401	mg	60000	55965
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		12.48	mg	12000	11193
encapsulation				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		15.601	mg	15001	13992
encapsulation				supplier	mold compound	Carbon black	1333-86-4		3.12	mg	3000	2798
connections coating	Solder	0.776	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.776	mg	1000000	696